

IEEE DTPI 2023

Call for Papers

7-9 November 2023 in Orlando, FL

2023.IEEE-DTPI.ORG



3rd Annual IEEE International Conference on Digital Twins and Parallel Intelligence

IEEE DTPI 2023 will present the cutting-edge research and technical progress of the rapidly evolving field of digital twinning. The 2023 Conference will follow a distributed hybrid model with physical meetings and presentations in Orlando and online. The conference aims to bring together scholars and industrial practitioners to share scientific and technological advances as well as to gain a deeper understanding of generating digital twins and deriving parallel intelligence. DTPI's particular topics also include standards, theory, practice, and various vertical applications of DTPI, including smart cities, transportation, energy, robotics, manufacturing, healthcare, spectrum management, etc.

Submissions are invited in the following categories:

FULL TECHNICAL PAPERS (4-6 pages), original contributions addressing relevant DTPI topics of interest listed in this CFP. Review, Tutorial and Vision papers are also welcome. Full technical papers will be submitted to Manuscript Central under the "DTPI 2023" issue. The papers will also receive consideration for direct publication in IEEE Journal on RFID. Authors of accepted papers are expected to present their work at the DTPI Conference in Orlando.

SPECIAL SESSIONS (by invitation), consisting of contributions to fill a two-hour session on DTPI topics of interest. Session proposals must be submitted electronically via e-mail (nedam@gatech.edu). A total of six accepted proposals will be invited to submit special session contributions.

EXTENDED ABSTRACTS (1-2 pages), consisting of a lightly reviewed, 1-2 pages abstracts on DTPI topics of interest to be presented in a poster presentation format at the conference.

INDUSTRIAL FORUM & EXHIBITIONS (IF&E), we additionally accept submissions of proposals for tutorials, demonstrations, posters, workshops and talks targeting cutting-edge, industry-centric topics. Trade space is available for discussions and demonstrations.

*The main technical program will only include papers of the highest standard as selected by the TPC, in accordance with the IEEE guidelines. Final manuscripts should be accompanied by a full registration of at least one author before uploading the camera-ready version. Accepted manuscripts will be presented either in oral or poster format.

Topics of interest include,
but not limited to:

Theory of Development for DTPI

Information Infrastructure for DTPI

**Data Analytics and Artificial
Intelligence R&D for DTPI**

DTPI Applications in Vertical Areas:

- Smart Cities
- Smart Infrastructure Systems
- Transportation
- Power & Energy Systems
- Autonomous Vehicles
- Human Systems
- Blockchain and Distributed Systems
- Ecology Digital Twins
- Cyber-Physical Social
- Decision Support Systems
- Healthcare
- Robotics
- Manufacture Systems

Industrial Practices of DTPI

Emerging DT Standards & Practices

Authors of Published Papers receive peer reviews by technology leaders from the multi-disciplinary IEEE DTPI and Council on RFID community and are enrolled in the IEEE DTPI 2023 Best Paper Competition.

Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements.

IEEE DTPI 2023 ORGANIZING COMMITTEE:

Executive Chair: Grace Bochenek
(Univ. of Central FL)

General Chair: Gisele Bennet
(MEPSS)

**Vice & Local
Arrangement Chair:** Mary Jean Amon
(Univ. of Central FL)

TPC Co-Chairs: Dirk Reiners (Univ.
of Central FL), Neda
Madi (Georgia Tech)

IMPORTANT DATES:

Full Technical Papers: 30 July 2023

Acceptance Notification: 24 Sep 2023

Poster Abstracts: 27 July 2023

Special Session Proposals: 27 July 2023

IF&E Proposals: 16 July 2023

Camera-Ready Uploads: 15 Oct 2023

Physical Conference: 7-9 November 2023